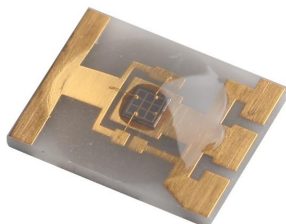


Peak Emission Wavelength: 1020nm



**Features:**

- size: 6.0(L) x 4.7(W) x 1.1(H) mm
- circuit substrate: AlN ceramics
- lead free solderable, soldering pads: gold plated
- devices are RoHs and REACH conform
- taped in 16 mm blister tape, cathode to transporting perforation
- all devices sorted into intensity classes
- taping: face-up (T)

Absolute Maximum Ratings (Ta=25°C)



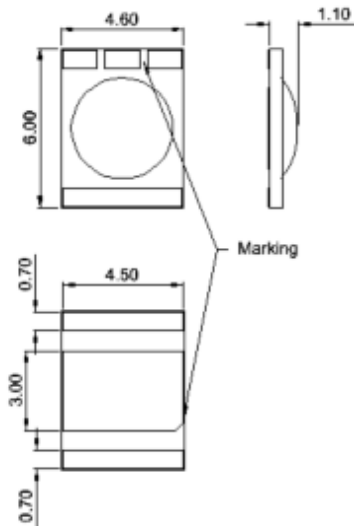
ITEMS	SYMBOL	RATINGS	UNIT
Forward DC Current	If	700	mA
Peak Forward Current *	Ifp	1000	mA
Reverse Voltage	Vr	5	V
Operating Temperature	Top	-40 to +85	°C
Storage Temperature	Tst	-40 to +85	°C
Thermal Resistance RthJA		5	K/W

\* tp ≤ 100 us, T=1:10

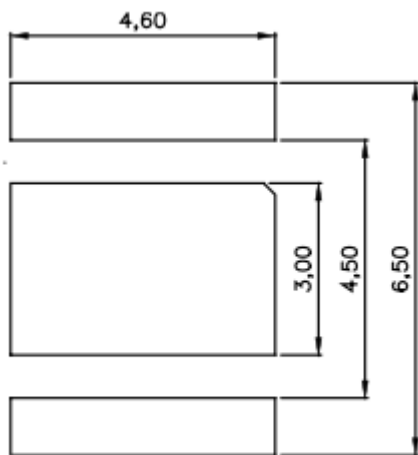
Electrical & Optical Characteristics (Ta = 25°C)

ITEMS	SYMBOL	CONDITION	MIN	TYP	MAX	UNIT
Reverse Current	Ir	Vr=5V	--	--	100	uA
Forward Voltage	Vf	If=350mA	--	1.2	1.5	V
Peak Wavelength	λp	If=350mA	1005	1020	1035	nm
Radiant Intensity	Ie	If=350mA	9	16	--	mW/sr
Spectral Bandwidth	Δλ	If=350mA	--	50	--	nm

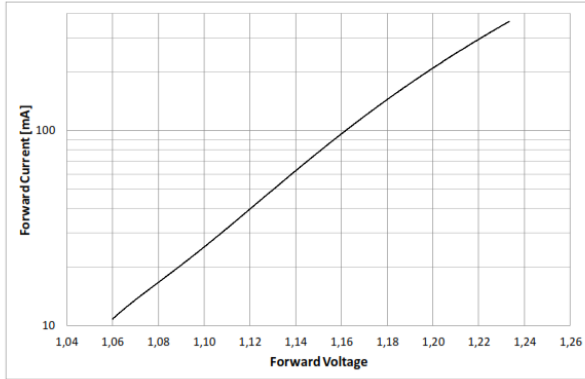
Package Dimensions



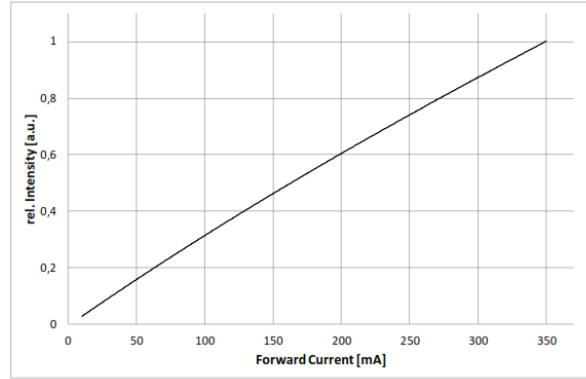
Marking at cathode  
Markierung an der Kathode



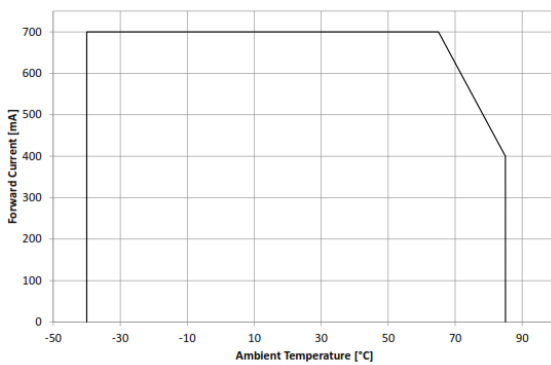
Recommended Soldering Pattern



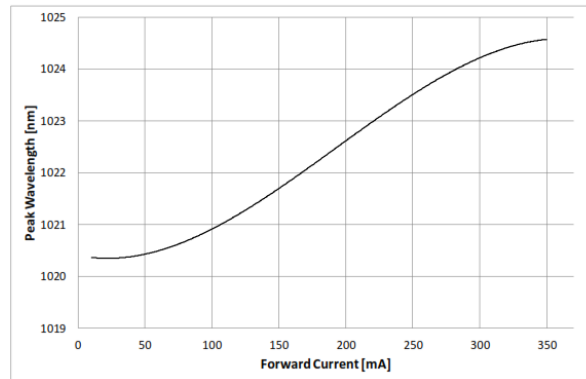
Forward Current vs. Forward Voltage



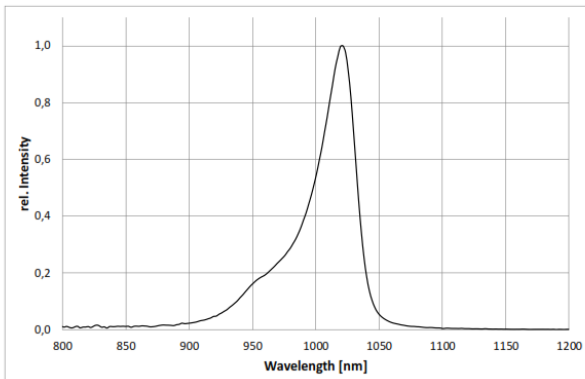
Intensity vs. Forward Current



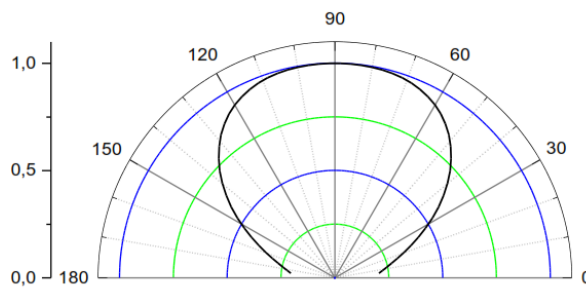
Max. Forward Current vs. Ambient Temperature



Shift Peak Wavelength vs. Forward Current

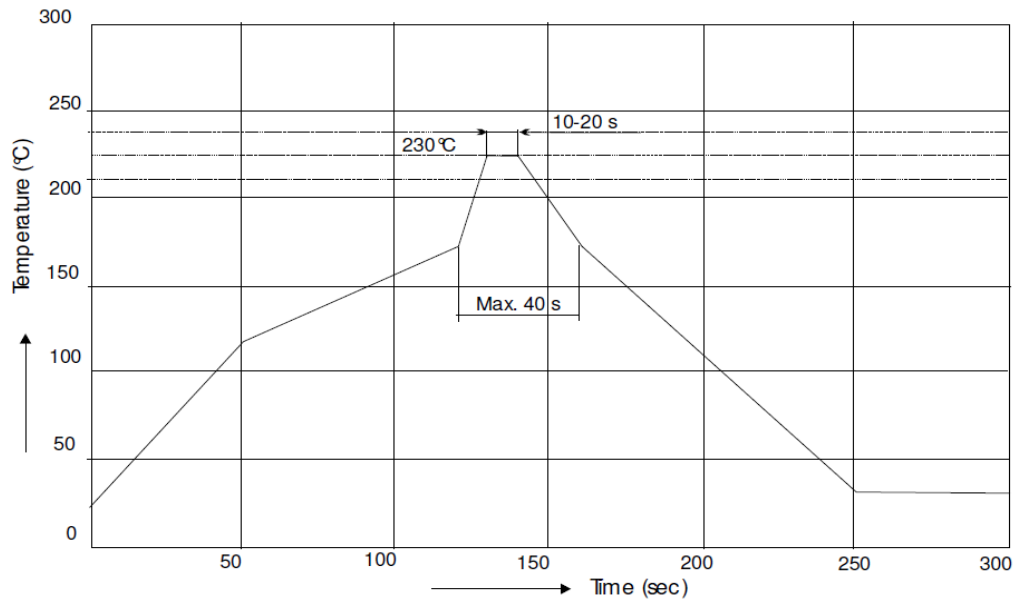


Spectrum

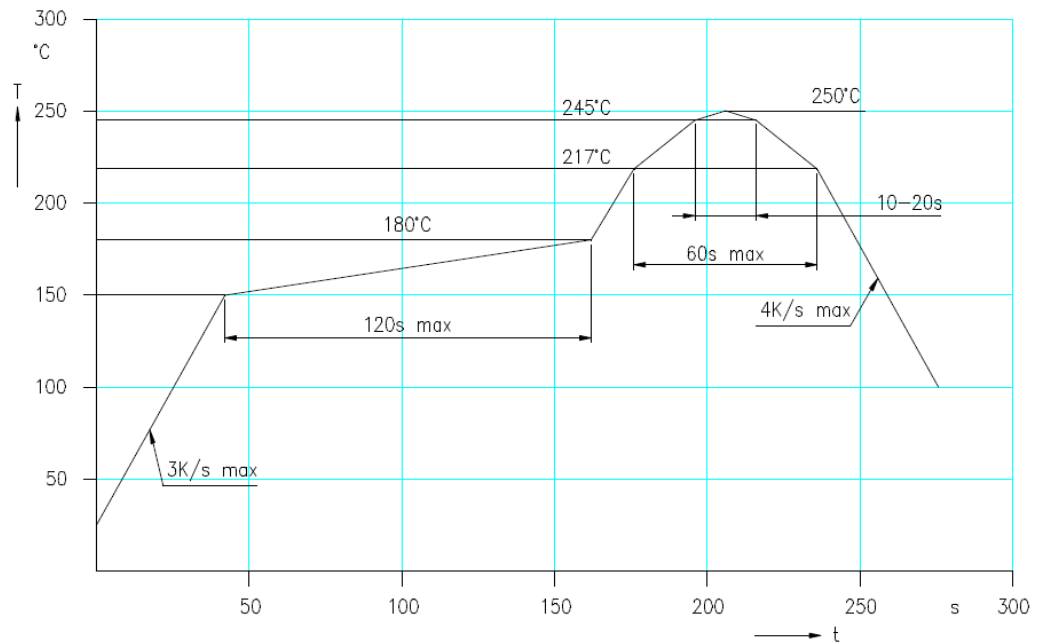


View Angle

**IR reflow soldering profile**

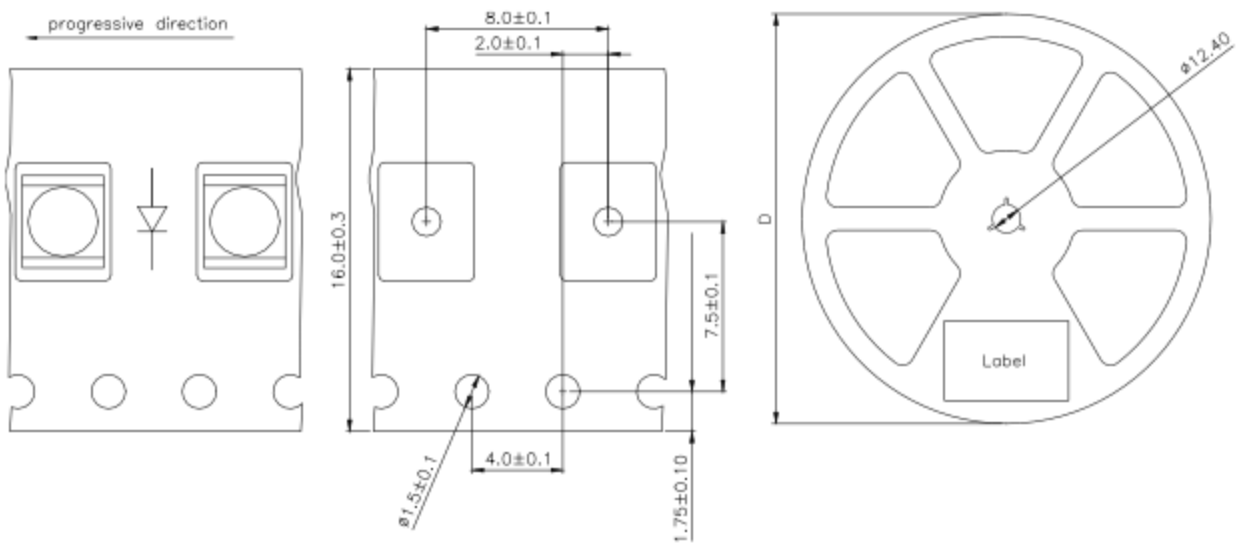


**IR reflow soldering profile for lead free soldering**



**Manual soldering:**  
max power of iron 25 W / 3 s / 300°C

• **Tape And Reel Packing**



The information contained herein is subject to change without notice.

2024-04-08